

## Features

- Size 0.18\*0.12 inch / 4.5\*3.2 mm
- Surface mount resettable fuse
- Fast time-to-trip
- Low resistance
- RoHS compliant, lead-free and halogen-free
- Compatible with high temperature solders

## Electrical Characteristics (25°C)/电性参数

Part Number	Marking	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	P <sub>d</sub> typ. (W)	Time to Trip (Max.)		Resistance	
							Current (A)	Time (Sec)	R <sub>min</sub> (Ω)	R <sub>1max</sub> (Ω)
1812L200/30GR	B200	2.00	4.00	30	40	1.4	8.00	2.00	0.020	0.100

I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 25°C still air. 保持电流=在 25°C 静止空气环境中,元件不动作的最大电流。

I<sub>trip</sub> = Trip current: minimum current at which the device will trip in 25°C still air. 动作电流=在 25°C 静止空气环境中,元件的最小动作电流。

V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>). 最大电压=元件在额定电流下能承受的最大电压。

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>). 最大电流=元件在额定电压下能承受的最大电流。

P<sub>d</sub> typ. = Typical power dissipated from device when in the tripped state at 25°C still air. 动作功率=在 25°C 静止空气环境中,元件动作状态下的消耗功率。

T<sub>trip</sub> = Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec. 动作时间=5 倍保持电流下的最大动作时间。

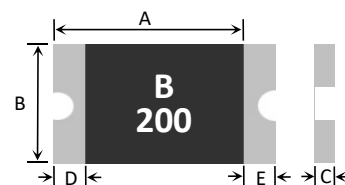
R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state. 初始最小电阻=元件焊接前的初始最小阻值。

R<sub>1max</sub> = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec. 焊后最大电阻=元件焊接 1 小时后的最大阻值。

**Caution:** Operation beyond the specified rating may result in damage and possible arcing and flame. 注意: 超出指定额定值的操作, 可能会导致损伤并可能产生电弧和火焰。

## Product Dimensions(mm)/产品尺寸

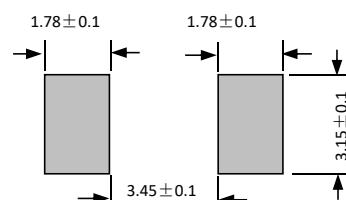
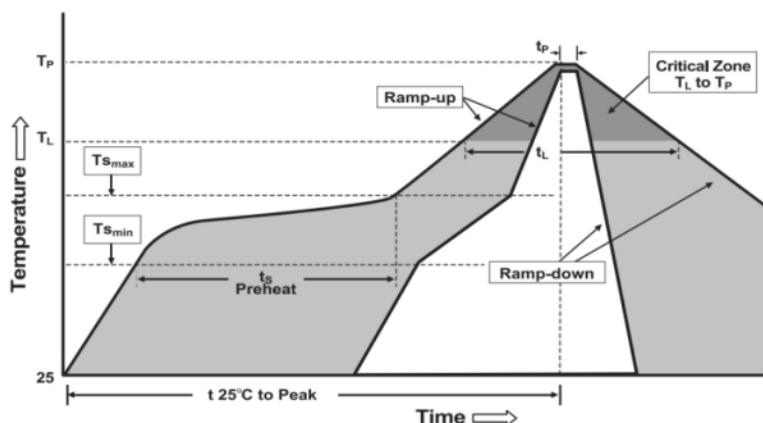
Part Number	Quantity	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
1812L200/30GR	1500	4.37	4.73	3.07	3.41	0.60	1.50	0.30	0.25



## Temperature Derating/不同环境温度下的 I<sub>hold</sub> 值

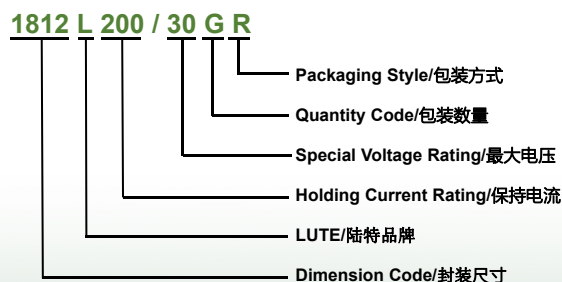
Part Number	Ambient operating temperature hold current (I <sub>hold</sub> )								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
1812L200/30GR	1500	4.37	4.73	3.07	3.41	0.60	1.50	0.60	0.30

## Solder Reflow Recommendations/回流焊建议



Recommended Pad Layout (mm)  
建议焊盘布局 (mm)

## Part Number System/产品编号



## Agency Approvals/认证

